Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1345743	pcb cb board ((printed circuit wiring) adj4 board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 15:42
L2	303877	(substrate carrier sheet flexible) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:53
L3	60746	(pad electrode terminal) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:57
L4	1234322	(chip die semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) same "4"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:53
L5	22800	(chip die semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 15:45
L6	6687	(assembly module unit) same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:54
L7	1868	(trace wiring) same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:54
L8	542942	(substrate carrier sheet flexible) and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:53

L9	213213	(chip die semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:54
L10	292739	(assembly module unit) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:54
L11	71389	(trace wiring) and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:55
L12	5443	6 and "11"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:55
L13	6687	6 and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:55
L14	3720	6 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:55
L15	1852	14 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:56
L16	1349	(ball bump mass bga) and 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:56

L17	1306	(component device) and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:56
L18	1306	(pad electrode terminal) and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 16:57